

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	35	"5306670"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:26
L9	32	"3192307"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:03
L10	64	"4246595"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:04
L11	24	"6038133"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:07
L12	23	"6154366"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:08
L13	26	"6271469"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:09
L14	4	"6292366"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:10
L15	5	"6475877"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:10
L16	5	"6538210"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:10
L17	9852	board with ((hole groove via recess) with (die chip 'ic'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:27

L18	19865	board with ((hole groove via recess) with (die chip 'ic' component))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:27
L19	4240	18 and ((hole groove via recess die chip 'ic' component) near5 (insulat\$3 dielectric))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:29
L20	1559	19 and laminat\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:29
L21	43	19 and (laminat\$3 near5 tape)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:29

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L23	4	board with ((hole groove via recess) with (die chip 'ic' component insulat\$3 dielectric) with (laminat\$3 with tape)).clm.	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/19 17:33